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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. Musser

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND  
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND  
THE LIKE

PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicants hereby petition for an extension of time of one month, extending the time for responding to the Office Action of April 24, 2003, to August 25, 2003, as August 24, 2003, falls on a Sunday.

A check for the statutory fee of \$110.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

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WASHINGTON OFFICE

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CUSTOMER NUMBER

Respectfully submitted,

John K. Shin  
Registration No. 48,409

Date: August 25, 2003

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9/3/03